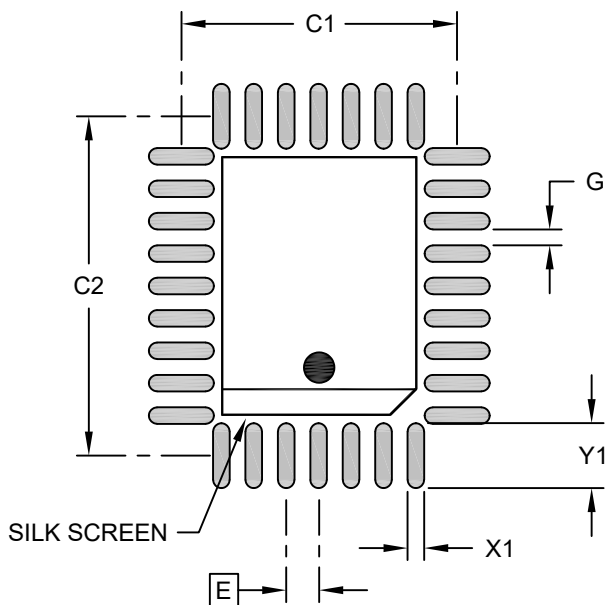


32-Lead Plastic Leaded Chip Carrier (L) - Rectangle [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	.050 BSC		
Contact Pad Spacing	C1		.425	
Contact Pad Spacing	C2		.524	
Contact Pad Width (X32)	X1			.026
Contact Pad Length (X32)	Y1			.100
Contact Pad to Center Pad (X28)	G	.008		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process